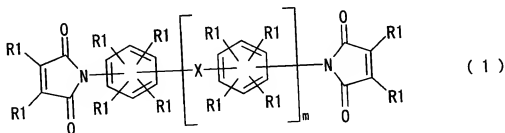


ABSTRACT

A heat resistance resin composition having superb low-temperature adhesiveness and a polyimide/metal laminate which is superior in solder heat resistance and hardly generates swelling when forming a Au-Sn bond or Au-Au bond, which are used for lead-free soldering and COF packaging. A metal laminate comprising a layer comprises a resin composition prepared by compounding a bismaleimide compound represented by the following formula (1) in a polyamic acid and/or a polyimide:



wherein m denotes an integer of 0 or more, each X independently represent O, SO₂, S, CO, CH₂, C(CH₃)₂, C(CF₃)₂ or a direct bond and each R₁ independently represents a hydrogen atom, a halogen atom or a hydrocarbon group and is independent of any other R₁ as to the substitution position on the benzene ring; and a metal foil layer, wherein the layer of the resin composition is formed on at least one surface of the metal foil layer. A resin composition for a metal laminate is also disclosed.